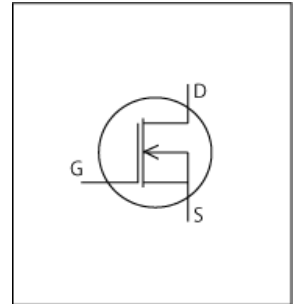


# LTspice Model

## NMOS

## STM

## STL50DN6F7



### Model Information

**Model** A macro model based on BSIM3 model  
**Call Name** MDC\_STL50DN6F7\_LT  
**Pin Assign** 1:S2 2:G2 3:S1 4:G1 5:D1 6:D1 7:D2 8:D2  
**File List** Model Library MDC\_STL50DN6F7\_LT01.lib  
 Model Report MDC\_STL50DN6F7\_LT.pdf (this file)

**Verified Simulator Version** LTspice version XVII  
**Note**

### References

The information which was used for modeling is as follow:

[Data Sheet]

- Date/Version November 2015 Rev 2
- Product name STL50DN6F7
- Company name STMicroelectronics N.V.
- Characteristics IdVds[Vgs], IdVgs[Temp], VgsQg[Vdd], Rds(on)Id[Vgs], CapacitanceVds[Cname], VthTemp[Id], Rds(on)Temp[Vgs], BvTemp[ir], VsdIs[Temp], SwitchingIdd[Tname], SwitchingWaveform, Trrrf[Ir], Qrrf[Ir], TrrrWaveform

### Simulation Range

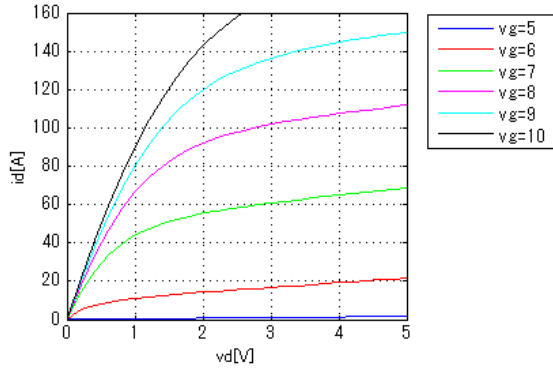
This table shows the range of evaluated simulation range that was not occurs any convergence problems in this area.

Item	Range			Unit
	Min.		Max.	
Drain-source voltage (DC)	0	to	60	V
Gate-source voltage (DC)	-20	to	20	V
Temperature	-55	to	175	deg C

Simulation results are following.  
 Explanatory notes — : simulated

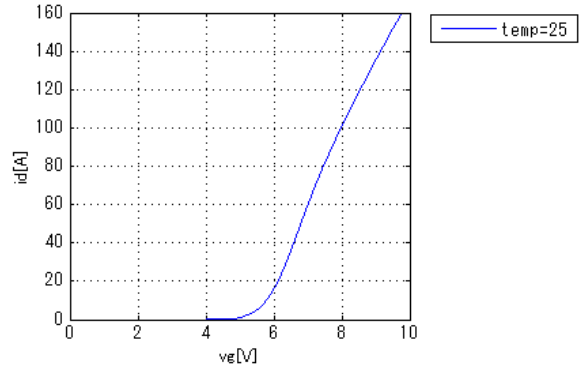
**IdVds[Vgs]**

Temp. = 25degC



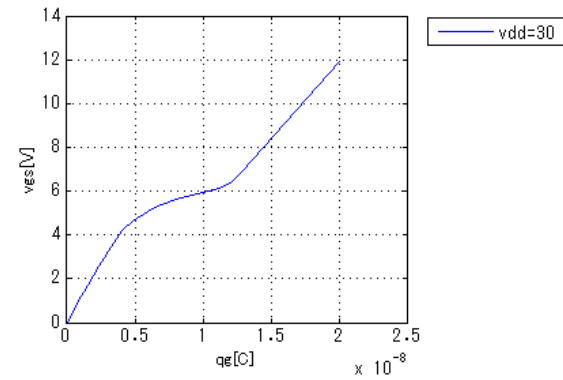
**IdVgs[Temp]**

Vds = 3V

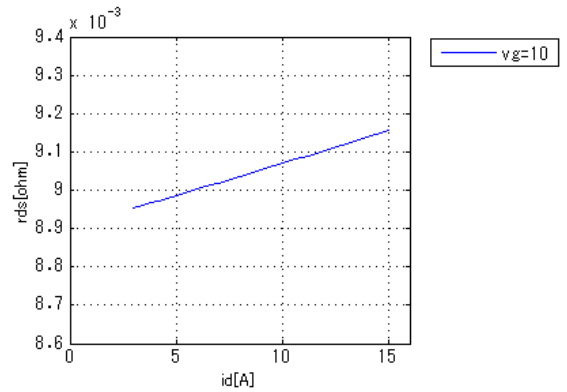


**VgsQg[Vdd]**

Id = 15A

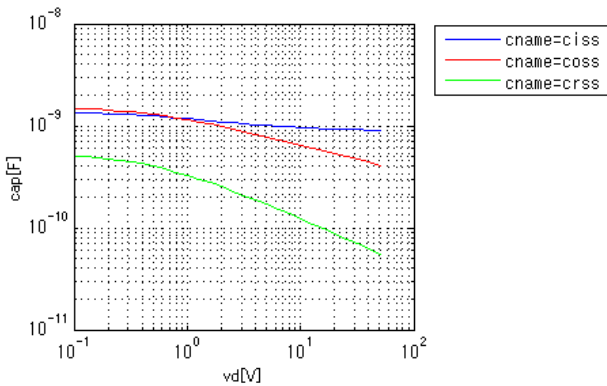


**Rds(on)Id[Vgs]**



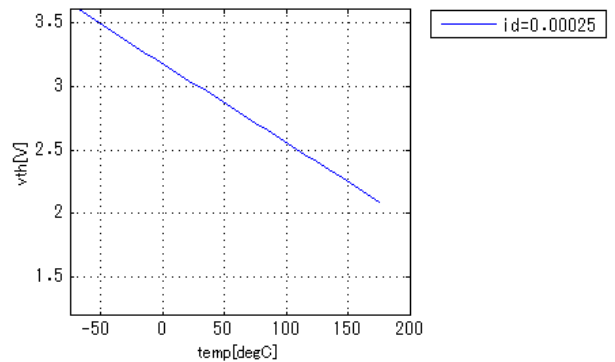
**CapacitanceVds[Cname]**

freq = 1000000Hz



**VthTemp[Id]**

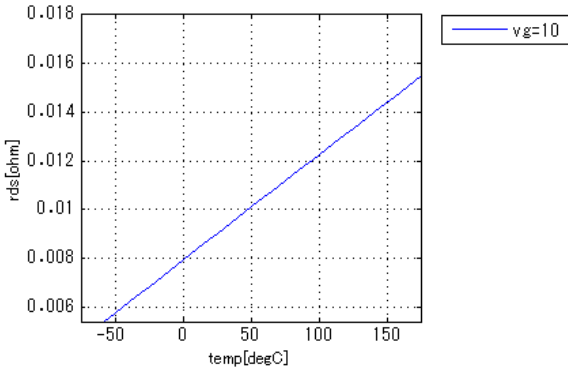
Vd = Vg



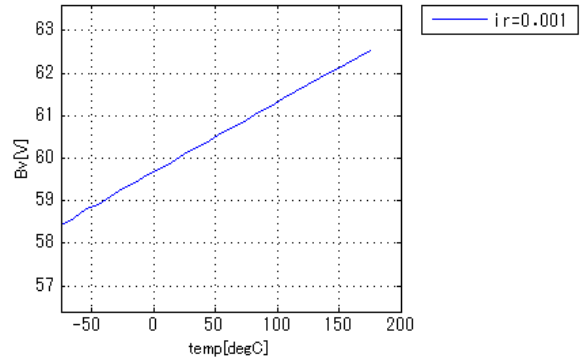
Simulation results are following.  
 Explanatory notes — : simulated

**Rds(on)Temp[Vgs]**

Id = 7.5A

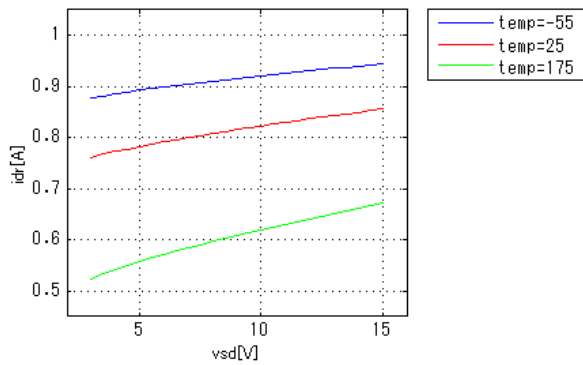


**BvTemp[ir]**



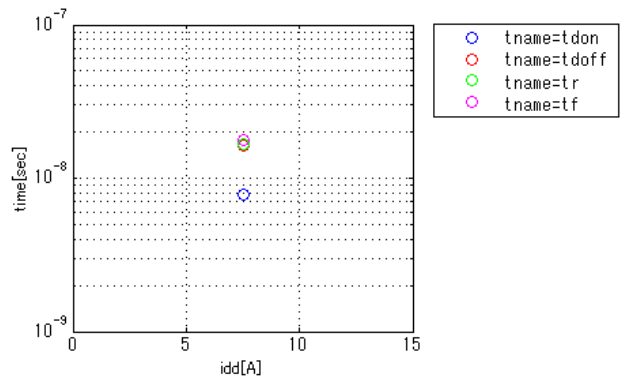
**Vsdl[Temp]**

vg = 0V



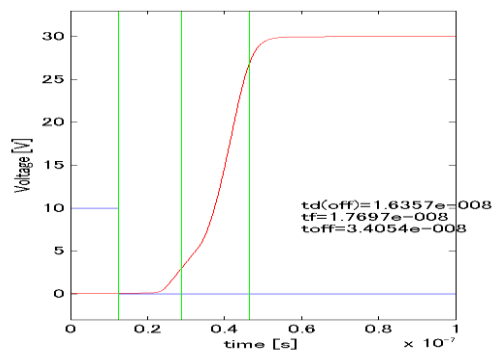
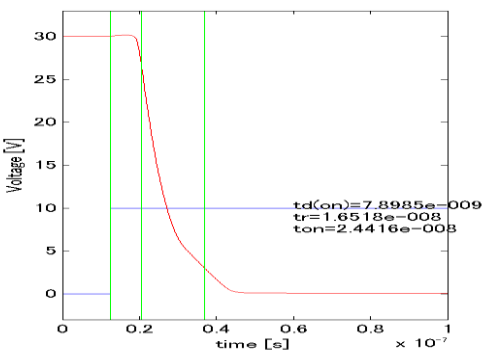
**SwitchingIdd[Tname]**

vgg = 10V, vdd = 30V, RGG = 4.7ohm



**SwitchingWaveform**

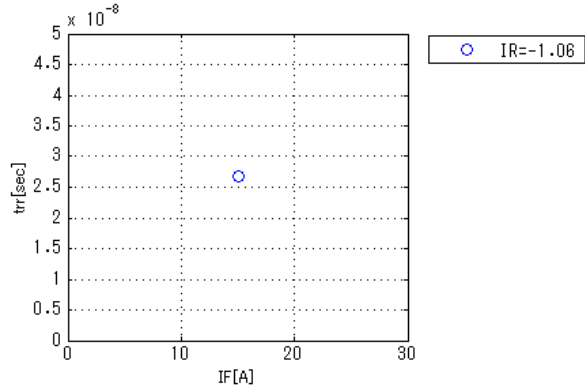
Blue : INPUT Red : OUTPUT



Simulation results are following.  
 Explanatory notes — : simulated

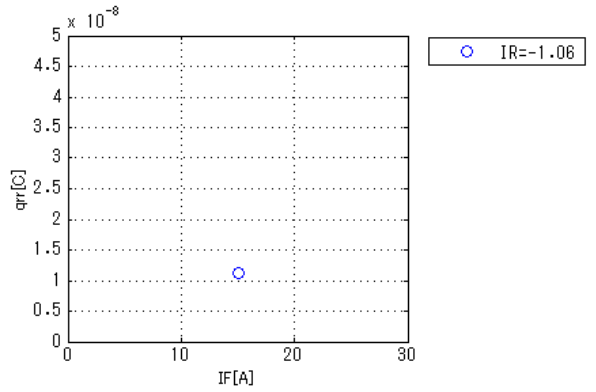
**Trrlf[Ir]**

vdd = 48V, didt = 100A/us

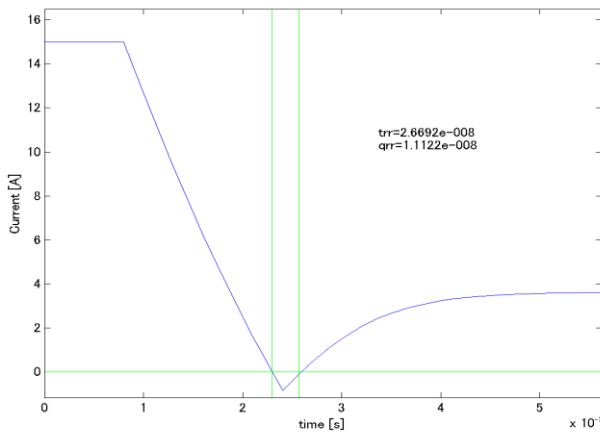


**Qrrlf[Ir]**

vdd = 48V, didt = 100A/us



**TrrQrrWaveform**



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